2000W BGA Reballing Machine with 0.02mm Placement Accuracy and 13×3-120×120mm Chip Size for Ball Grid Array Rework Station

Our Product Introduction

Basic Information

- Brand Name: WISDOMSHOW
- Certification: CE
- Model Number: DS-300
- Minimum Order Quantity: 1pcs
- Packaging Details: wood carton
- Delivery Time: 5-8 working days
- Payment Terms: T/T
- Supply Ability: 200Sets / Month



Product Specification

- Power Supply: AC220V 50Hz
- Air Source: 0.4-0.8Mpa
- Applicable Chip Size: 13×3-120×120mm
- Placement Accuracy: 0.02mm
- Total Power: 2000W
- Solder Ball Size Range: 0.2-1.27mm
- Highlight: **2000W BGA Reballing Machine**, **0.02mm Placement Accuracy Ball Grid Array Rework Station** , **13×3-120×120mm Chip Size BGA Reballing Machine**

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Product Description

Product Description:

The BGA Reballing Machine is a highly advanced and efficient Ball Grid Array Rework Station designed to meet the precise demands of modern electronics manufacturing and repair. This state-of-the-art BGA Chip Reballing System offers exceptional accuracy and reliability, making it the ideal choice for technicians and engineers involved in the reballing and refurbishment of BGA chips. With its robust construction and cutting-edge technology, the machine ensures consistent performance and superior results in every use.

One of the standout features of this BGA Reballing Machine is its impressive placement accuracy of 0.02mm. This high level of precision ensures that solder balls are positioned perfectly on the chip, which is critical for maintaining the electrical and mechanical integrity of the reworked component. The machine supports a solder ball size range from 0.2mm to 1.27mm, providing great versatility to handle a wide variety of BGA chip sizes and specifications. Whether dealing with fine-pitch chips or larger grid arrays, this system accommodates the specific needs of each task with ease.

Powered by a reliable AC220V 50Hz power supply and consuming a total power of 2000W, the BGA Chip Reballing System delivers consistent energy output for stable operation. This power configuration allows the machine to handle demanding reballing processes without compromise, ensuring efficient heat management and consistent solder ball placement. Additionally, the machine operates with an air source pressure range of 0.4-0.8Mpa, which contributes to the smooth and controlled handling of solder balls during the reballing process. This air pressure specification is optimized to provide stable airflow, enhancing the overall precision and reducing the risk of errors or damage to delicate components.

Designed with user convenience and operational efficiency in mind, the Ball Grid Array Rework Station features an intuitive interface and ergonomic design. The system allows for quick setup and easy adjustment of parameters, enabling operators to switch between different solder ball sizes and chip types without hassle. This flexibility reduces downtime and increases throughput, making it an excellent investment for production environments as well as repair workshops.

Furthermore, the BGA Chip Reballing System is engineered to deliver consistent, high-quality reballing results, which significantly extend the lifespan and functionality of BGA chips. By restoring the solder ball array with precision, the system helps prevent connectivity issues and enhances the reliability of the repaired devices. This capability is particularly valuable in sectors such as consumer electronics, telecommunications, automotive electronics, and aerospace, where the performance of BGA components is critical.

In summary, the BGA Reballing Machine is a comprehensive solution for anyone looking to achieve precise and reliable reballing of Ball Grid Array chips. Its combination of high placement accuracy, versatile solder ball size compatibility, stable power supply, and optimized air source pressure makes it a top-tier BGA Chip Reballing System. Whether for prototyping, small-scale repair, or large-scale production, this machine delivers outstanding performance and value, ensuring that every reballing task is completed with the utmost quality and efficiency.

Features:

Product Name: BGA Reballing Machine

High Placement Accuracy: 0.02mm for precise solder ball placement

Applicable Chip Size Range: Supports chips from 13*3mm up to 120*120mm

Power Supply: AC220V 50Hz ensuring stable operation

Solder Ball Size Range: Compatible with solder balls sized 0.2-1.27mm

Air Source Requirement: 0.4-0.8Mpa for optimal performance

Also known as BGA Soldering Repair Machine, ideal for efficient BGA chip repair

Functions as a BGA Chip Reballing System for reliable ball grid array refurbishment

Serves as a Ball Grid Array Rework Station to facilitate precise reballing and soldering tasks

Technical Parameters:

Applicable Chip Size	13*3-120*120mm
Solder Ball Size Range	0.2-1.27mm
Power Supply	AC220V 50Hz
Total Power	2000W
Air Source	0.4-0.8Mpa
Placement Accuracy	0.02mm

This Ball Grid Array Rework Station is an advanced BGA Chip Reballing System and BGA Soldering Repair Machine designed for precise and efficient chip reballing tasks.

Applications:

The WISDOMSHOW DS-300 Ball Grid Array Rework Station is an advanced BGA Chip Reballing System designed for precision and efficiency in electronics repair and manufacturing. Originating from Shenzhen, China, this high-performance machine is equipped with a power supply of AC220V 50Hz and requires an air source of 0.4-0.8Mpa, ensuring stable operation in various work environments. Its outstanding placement accuracy of 0.02mm makes it ideal for delicate and intricate reballing tasks, where precision is paramount.

This Ball Grid Array Rework Station is perfect for occasions that demand meticulous reballing of BGA chips, such as electronics repair centers, manufacturing plants, and quality control laboratories. It supports solder ball sizes ranging from 0.2mm to 1.27mm, accommodating a wide range of applications and chip specifications. The DS-300 model is capable of handling chip sizes from as small as 13*3mm up to 120*120mm, making it versatile enough for small-scale mobile device components to larger, more complex circuit boards.

In scenarios where electronic devices need refurbishment or repair, the WISDOMSHOW BGA Chip Reballing System plays a crucial role. It is widely used in repairing smartphones, tablets, gaming consoles, laptops, and other consumer electronics where Ball Grid Array components are prevalent. The machine's precise ball placement ensures reliable solder joints, which are critical for restoring device functionality and prolonging product lifespan.

Additionally, the DS-300 Ball Grid Array Rework Station is indispensable during the prototyping and production phases in electronic manufacturing. Engineers and technicians use it to reball defective or outdated BGA chips, enabling cost-effective reuse and reducing electronic waste. Its user-friendly design and high accuracy make it a valuable tool for both small repair shops and large-scale manufacturing lines.

Overall, the WISDOMSHOW DS-300 BGA Reballing Machine excels in any professional setting that requires precise, reliable, and efficient reballing of BGA chips. Whether for repair, refurbishment, or production, this Ball Grid Array Rework Station delivers superior performance and versatility, making it a trusted choice in the electronics industry.

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